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**PRIMA-BOND**  
**ME7155-SC4**

- Stress Free**
- Solvent Free**
- Thermally Conductive**
- Reworkable**
- Epoxy Paste Adhesive**

**IDEAL FOR:**

- Thermal Management
- Reworkability
- Mismatched CTE's
- Curing During Solder Reflow of S.M. Devices

**DESCRIPTION:**

ME7155-SC4 is a reworkable, alumina filled, electrically insulating and thermally conductive epoxy paste adhesive. It exhibits outstanding flexibility for bonding materials having highly mismatched CTE's. The high thermal conductivity of this material makes it useful as a thermal bridge between surface mount components and substrates where heat dissipation is critical for thermal management.

ME7155-SC4 cures during the reflow soldering of surface mount components. It can be readily reworked at 80-100°C.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 60 minute )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	-25 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	>1000 psi >6.9 N/mm <sup>2</sup>
Device Push-off Strength	>1500 psi >10.3 N/mm <sup>2</sup>
Hardness (Type)	Not Available ±10%
Cured Density (gm/cc)	2.3 ±10%
Thermal Conductivity	12 Btu-in/hr-ft <sup>2</sup> -°F ±10% 1.7 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	120 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(0.5 rpm, 24°C) (Brookfield DV-1,spindle CP51)	270,000 cp ±20%

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**AVAILABILITY:**

ME7155-SC4 is available in syringes for automatic needle dispense applications or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw at room temperature for at least 30 minutes before using.
- ( 2 ) Dispense adhesive onto clean substrate.
- ( 3 ) Cure according to one of the recommended schedules.

**CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
100°C	60 min	
125°C	30 min	
150°C	5 min	

**SHELF LIFE:**

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details. The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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